

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2570512

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HUNG-DER SU	10/04/2013
CHIEN-WEI CHIU	10/04/2013
TSUNG-YI HUANG	10/04/2013
RECEIVING PARTY DATA	
Name:	RICHTEK TECHNOLOGY CORPORATION
Street Address:	5F. NO. 20, TAI YUEN STREET
City:	ZHUBEI CITY, HSINCHU
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14048971
CORRESPONDENCE DATA	
Fax Number:	(248)540-4035
Phone:	248-540-4040
Email:	tungassoc@aol.com
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>	
Correspondent Name:	TUNG & ASSOCIATES / RANDY W. TUNG, ESQ.
Address Line 1:	838 W. LONG LAKE RD.
Address Line 2:	SUITE 120
Address Line 4:	BLOOMFIELD HILLS, MICHIGAN 48302
ATTORNEY DOCKET NUMBER:	92000-356 (RH-1228)
NAME OF SUBMITTER:	RANDY W TUNG
Signature:	/Randy W Tung/
Date:	10/08/2013
Total Attachments: 1 source=s-356assn#page1.tif	

OP \$40.00 14048971

92000-356

RH-1228 V101-091

ASSIGNMENT

WHEREAS, I/we, Hung-Der Su, Chien-Wei Chiu, and Tsung-Yi Huang, have invented certain improvements in:

**“SEMICONDUCTOR COMPOSITE FILM WITH HETEROJUNCTION AND
MANUFACTURING METHOD THEREOF”**

for which I am/we are about to make application for Letters Patent of the United States; and

WHEREAS, Richtek Technology Corporation, a company having a business address residing in R.O.C., is desirous of acquiring the entire right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, I/we, Hung-Der Su, Chien-Wei Chiu, and Tsung-Yi Huang, by these presents, do hereby sell, assign and transfer unto the said corporation and its assigns, for the territory of the United States of America and all foreign countries, the entire right, title and interest, including all priority rights under the International Convention associated with each country of the Union, in and to said invention as described in the patent application executed by us on the following execution date, preparatory to obtaining Letters Patent of the United States thereon, and in and to said application and any Letters Patent that may be granted in pursuance of said application and any divisional, continuation or continuation-in-part application thereof, and in and to any reissue of any such patent, and in and to any patent applications which may be filed on said invention in countries foreign to the United States and any Letters Patent granted thereon.

I/we further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and I/we further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.

<u>Hung-Der Su</u>	<u>10/4/2013</u>
(Signature by first inventor/assignor)	(Date)
<u>Chien-Wei Chiu</u>	<u>10/4/2013</u>
(Signature by second inventor/assignor)	(Date)
<u>Tsung-Yi Huang</u>	<u>10/4/2013</u>
(Signature by third inventor/assignor)	(Date)

TUNG & ASSOCIATES

838 W. Long Lake Road, Suite 120
Bloomfield Hills, Michigan 48302

PATENT

Tsung-Yi Huang-04/10/2013 15:16

RECORDED: 10/08/2013**REEL: 031367 FRAME: 0742**